

CPAD 2023 - November 7th 2023

Design and characterization of sub-10ps TDC ASIC in 28nm CMOS technology for future 4D trackers

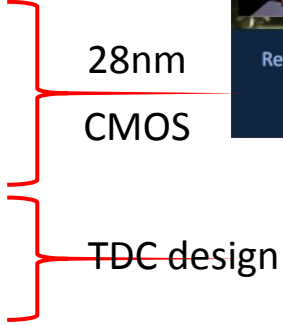
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Motivation

2019 DOE Basic Research Needs Study on High Energy Physics Detector Research and Development

- Future high energy, high luminosity hadron colliders will present much higher levels of pileup and extreme radiation environments
- Future detectors will require higher segmentation (3D position resolution) and additional time resolving capabilities while sustaining higher radiation doses (**Instrumentation BRN – Science Driver: Higgs and the energy frontier - PRD10, PRD16, PRD17, PRD18, PRD19, PRD20**)*
- To satisfy requirements front-end sensors and readout ASICs will need to be compatible with:
 - Larger channel density – Low power, Smaller feature size (Deep sub-micron technologies)
 - Unprecedented radiation levels (dose of up to 30 GRad and 10^{18} neutrons/cm²)
 - Precision timing resolution – fast sensors, in pixel high precision timing circuits



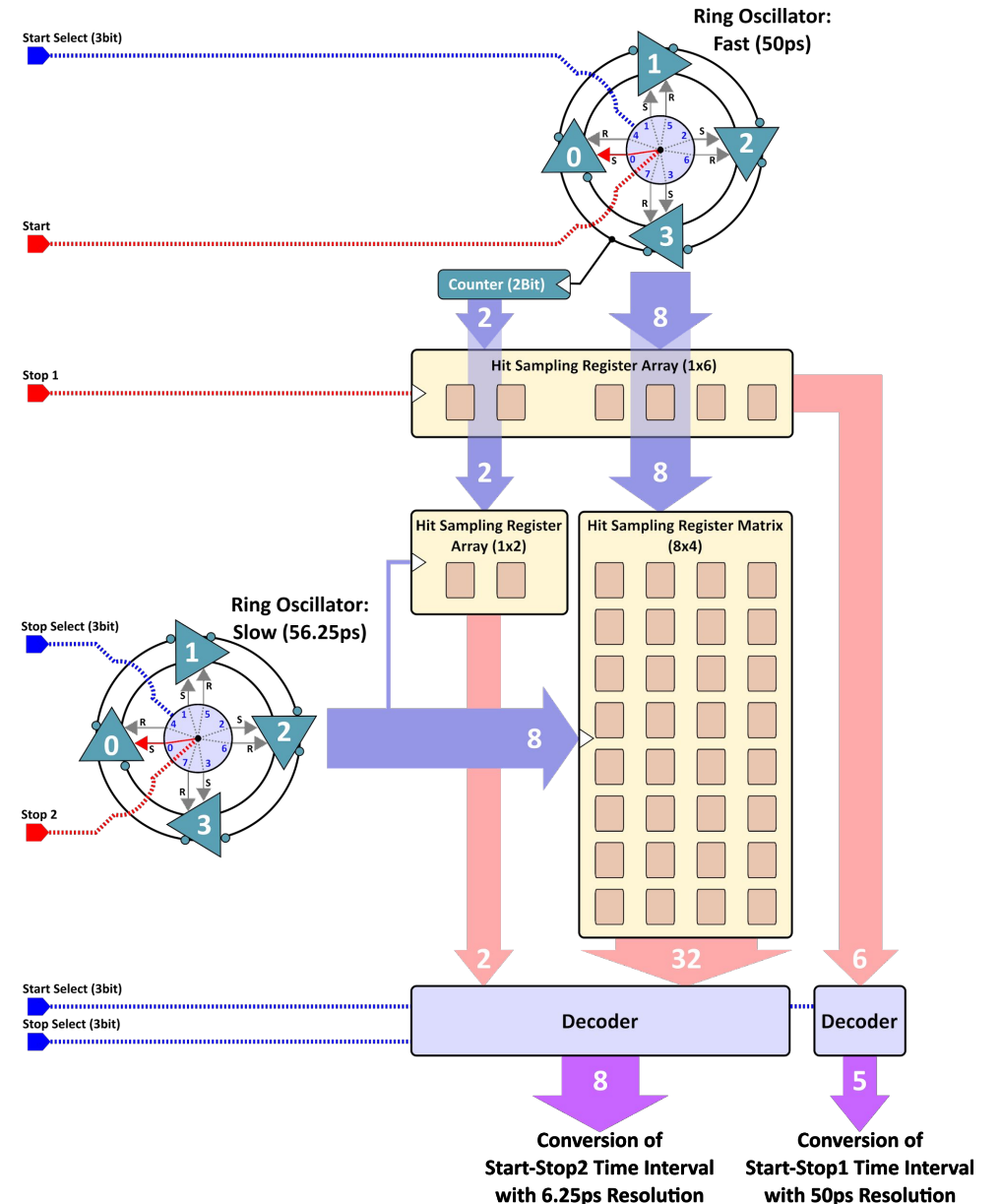
Basic Research Needs for High Energy Physics Detector Research & Development

	PRD: Priority Research Direction	Grand Challenge
Calorimetry	PRD 1: Enhance calorimetry energy resolution for precision electroweak mass and missing-energy measurements	1
	PRD 2: Advance calorimetry with spatial and timing resolution and radiation hardness to master high-rate environments	1,4
	PRD 3: Develop ultrafast media to improve background rejection in calorimeters and particle identification detectors	1,3,4
Nobles	PRD 4: Enhance and combine existing modalities to increase signal-to-noise and reconstruction fidelity	1,2
	PRD 5: Develop new modalities for signal detection	1
Photodetectors	PRD 6: Improve the understanding of detector microphysics and characterization	1
	PRD 7: Extend wavelength range and develop new single-photon counters to enhance photodetector sensitivity	1,3
	PRD 8: Advance high-density spectroscopy and polarimetry to extract all photon properties	2,3
	PRD 9: Adapt photosensors for extreme environments	2,4
	PRD 10: Design new devices and architectures to enable picosecond timing and event separation	1,2,4
Quantum	PRD 11: Develop new optical coupling paradigms for enhanced or dynamic light collection	1,2,3
	PRD 12: Advance quantum devices to meet and surpass the Standard Quantum Limit	1,3
	PRD 13: Enable the use of quantum ensembles and sensor networks for fundamental physics	1,2
	PRD 14: Advance the state of the art in low-threshold quantum calorimeters	1,3
	PRD 15: Advance enabling technologies for quantum sensing	1,2,3
ASIC	PRD 16: Develop process evaluation and modeling for ASICs in extreme environments	3,4
	PRD 17: Create building blocks for Systems-on-Chip for extreme environments	1,4
SolidState	PRD 18: Develop high spatial resolution pixel detectors with precise high per-pixel time resolution to resolve individual interactions in high-collision-density environments	1,4
	PRD 19: Adapt new materials and fabrication/integration techniques for particle tracking	2,3
	PRD 20: Realize scalable, irreducible-mass trackers	2,3
TDAQ	PRD 21: Achieve on-detector, real-time, continuous data processing and transmission to reach the exascale	2,4
	PRD 22: Develop technologies for autonomous detector systems	2
	PRD 23: Develop timing distribution with picosecond synchronization	1
Xcut	PRD 24: Manipulate detector media to enhance physics reach	1,3
	PRD 25: Advance material purification and assay methods to increase sensitivity	1,2,3,4
	PRD 26: Addressing challenges in scaling technologies	2,3

*Similar Detector Research and Development Themes (DRDTs) are identified in the 2021 European Committee for Future Accelerators (ECFA) Detector R&D (DRD) Roadmap

28nm TDC Architecture

- 2D Vernier Architecture:**
 - Fast Ring Oscillator with 50ps propagation delay cells;
 - Slow Ring Oscillator with 56.25ps propagation delay cells;
- START + two STOP signal for simultaneous Time-Of-Arrival (TOA) and Time-Over-Threshold (TOT) measurements;
- Start-Stop1 - Coarse time resolution (TOT): 50ps;
- Start-Stop2 - Fine time resolution (TOA): 56.25ps - 50ps = 6.25ps;
- Sliding scale technique for improvement of conversion linearity:**
 - Both ring oscillators have programmable starting conditions via delay cell set/reset function;
 - Starting conditions randomly selected each measurement cycle and corresponding values subtracted from the conversion result;
 - Same time intervals converted with different parts/bins of the TDC conversion characteristics;
 - Sliding scale transforms the non-linearities into stochastic variable thus effectively improving the conversion linearity at the expense of worsening single-shoot precision.

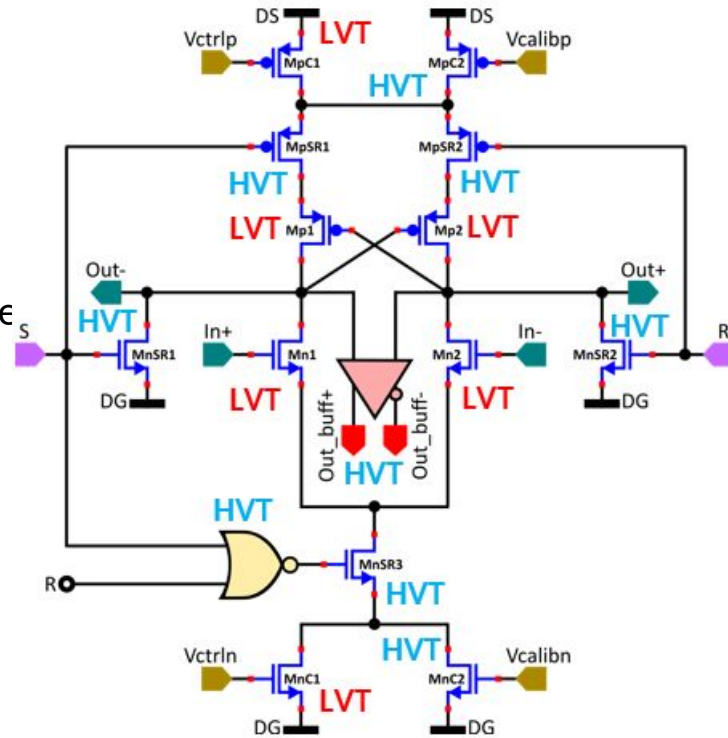


Voltage-Controlled Delay Cell (VCDC)

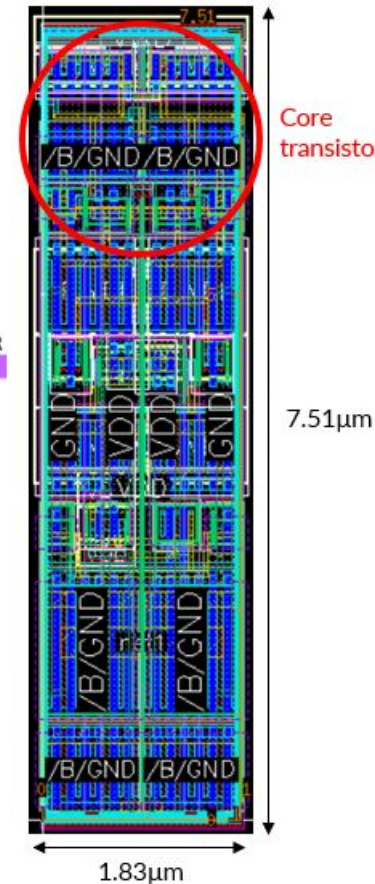
- ❑ Differential Cascode Voltage Switch Logic (DCVSL) implementation
- ❑ Current-starved approach for propagation delay control
- ❑ Calibration / Trimming
- ❑ Output buffer for driving the state-sampling registers
- ❑ **Set/Reset logic controls**
- ❑ Leakage reduction*:

- Non-minimum length (35nm) used for all transistors
- **Low Voltage Threshold (LVT) used for speed-critical transistors**
- **High Voltage Threshold (HVT) transistors in series between supply and ground**

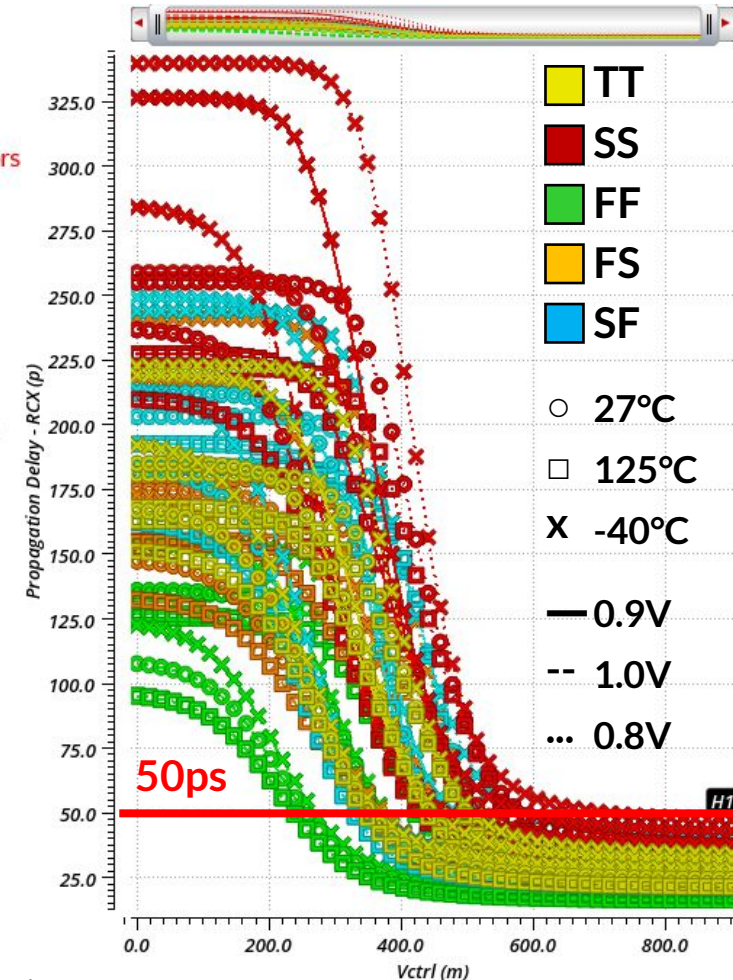
❑ Schematic:



❑ Layout:

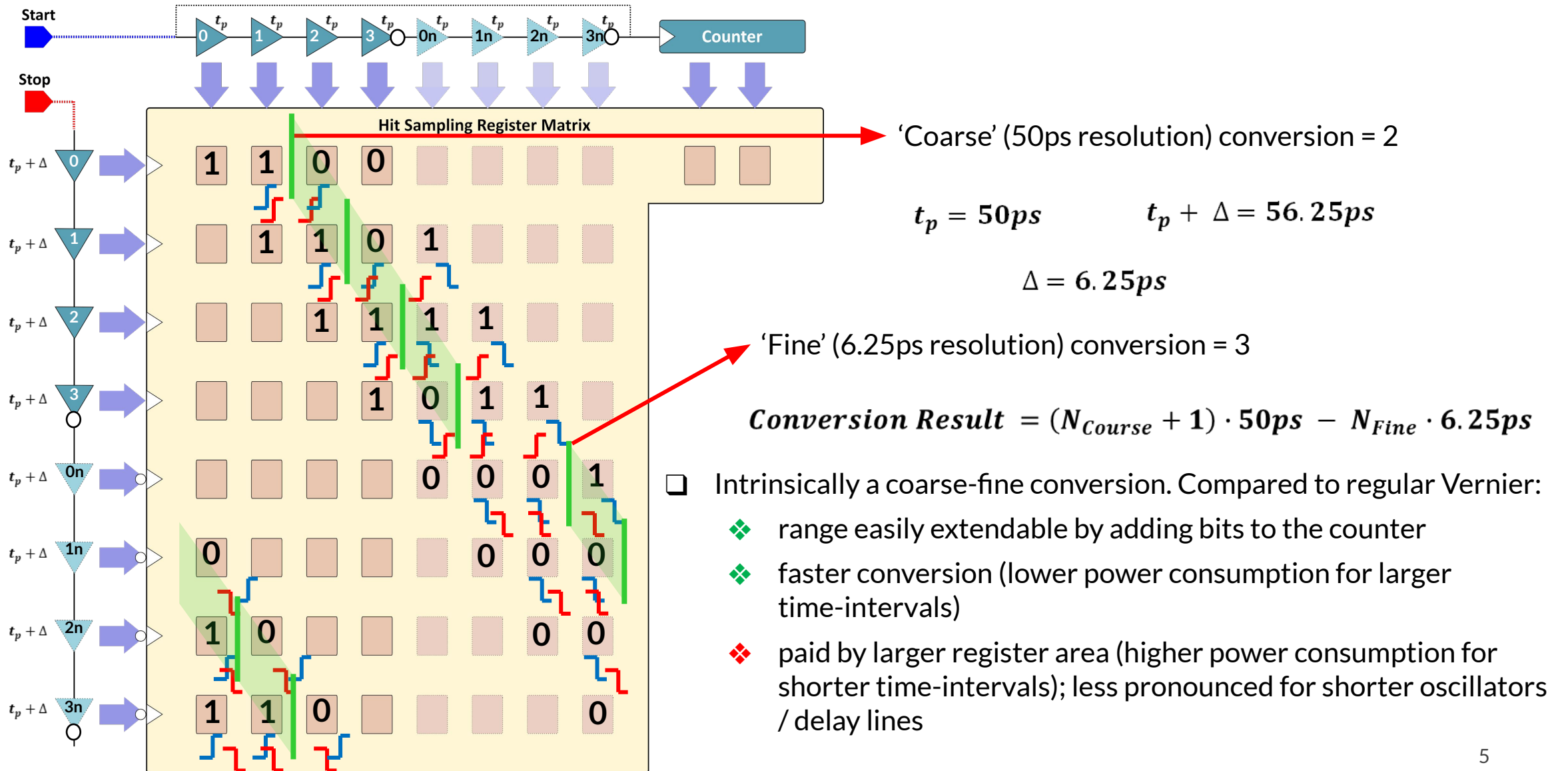


❑ Delay-Voltage Characteristics (RCX):



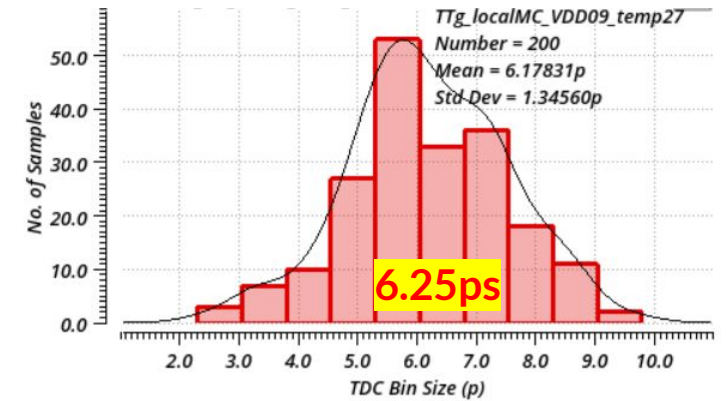
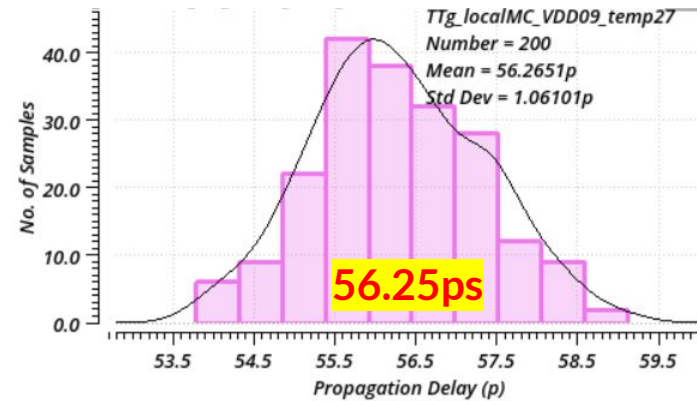
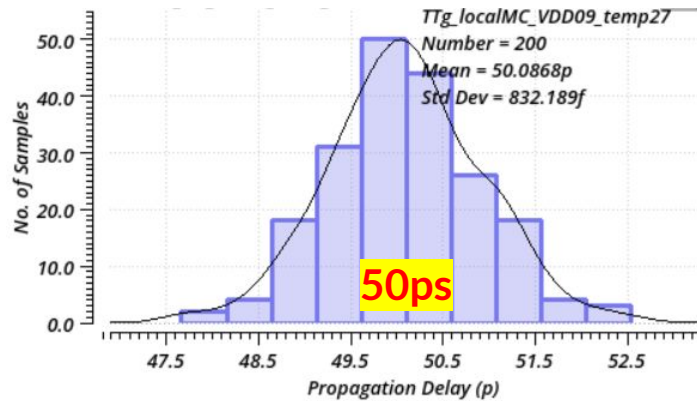
*technology simulations show significant leakage currents, making the logic static power consumption not negligible (especially at higher temperatures)

2D Vernier TDC - Operation

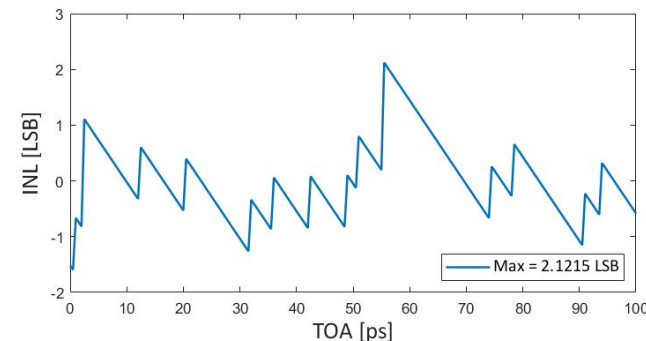
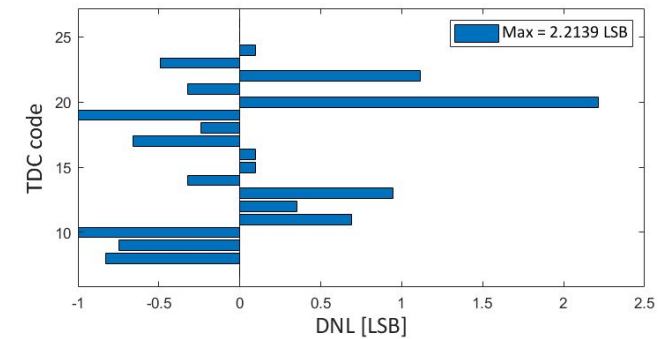
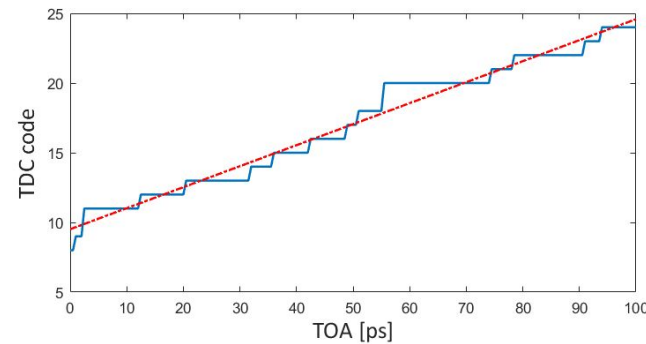


2D Vernier TDC – Mismatch (sliding scale disabled)

□ Delay Cell Mismatch (RCX, Global Corner + Local MC, N° of runs: 200):

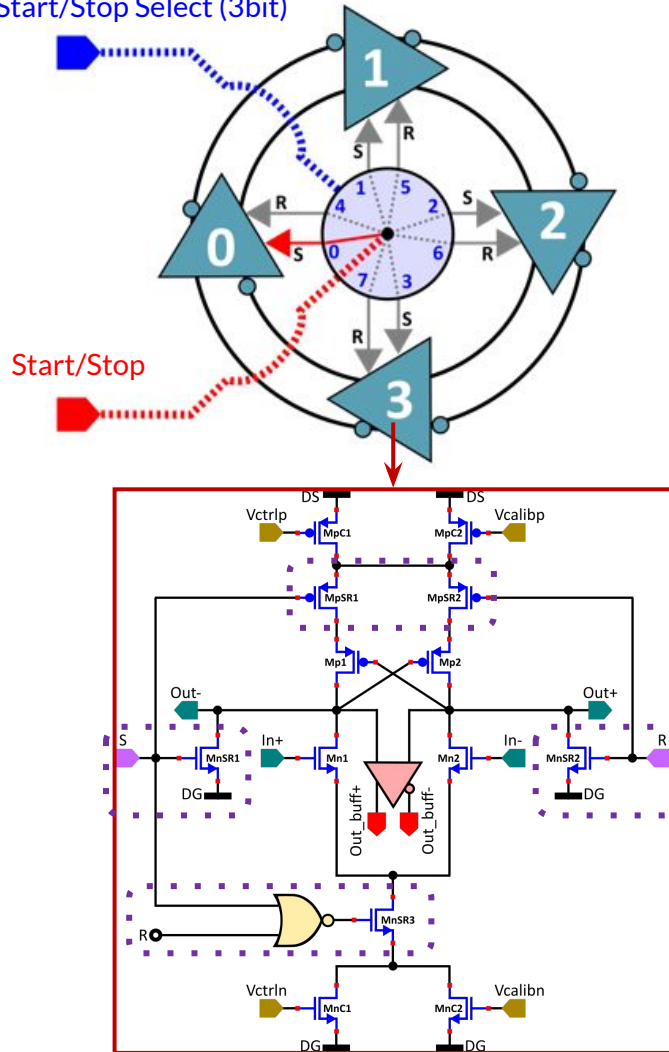


□ 2D Vernier TDC characteristics with mismatch (Global Corner + Local MC, one iteration):



Sliding-Scale Implementation

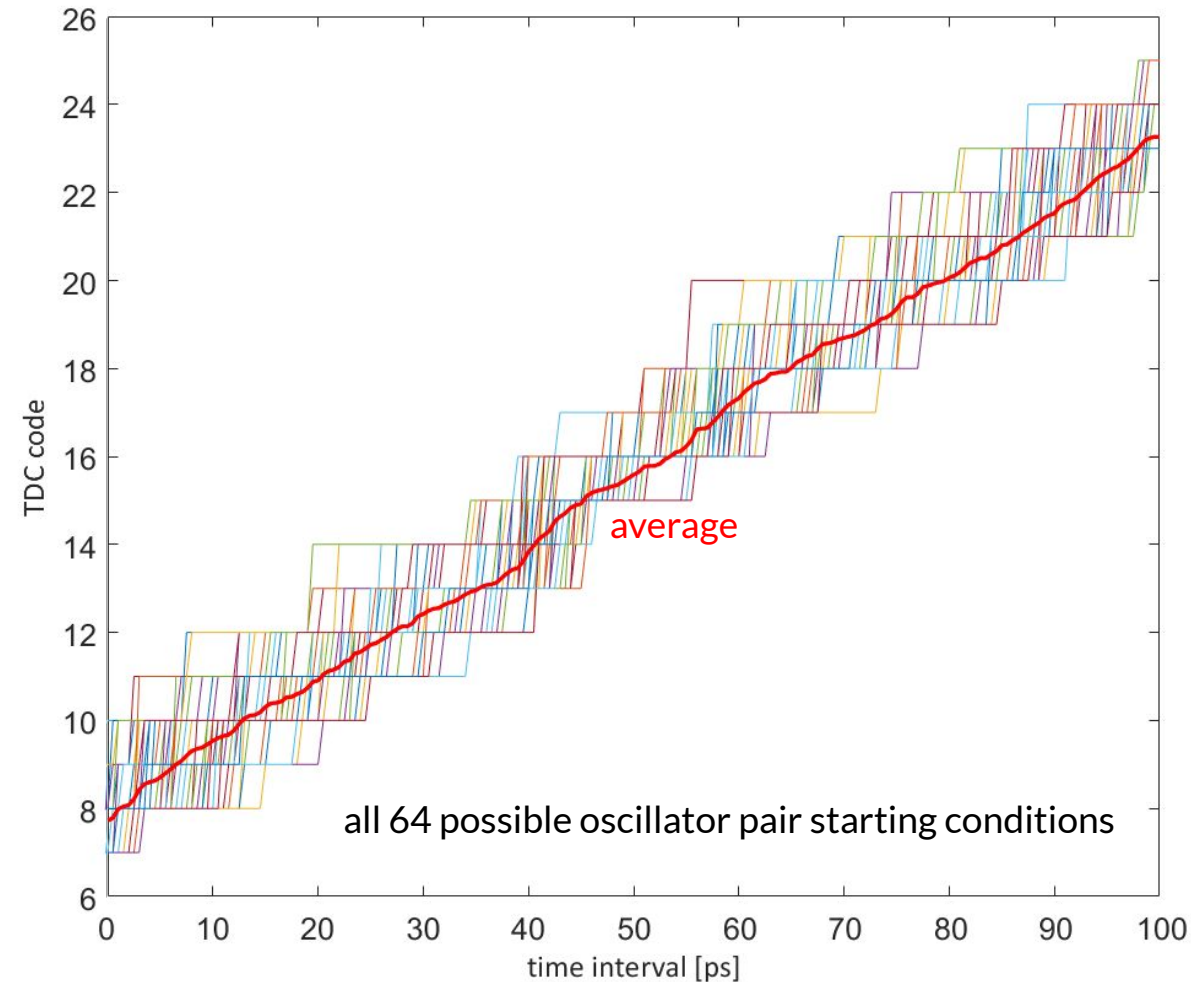
Start/Stop Select (3bit)



Sliding-Scale technique [1,2]:

- Both ring oscillators have programmable starting conditions via delay cell **set/reset** function;
- Starting conditions randomly selected each measurement cycle and corresponding values subtracted from the conversion result;
- Same time intervals converted with different parts/bins of the TDC conversion characteristics;

□ TDC characteristics with mismatch:

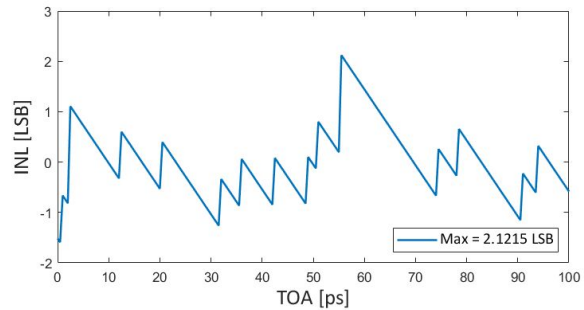
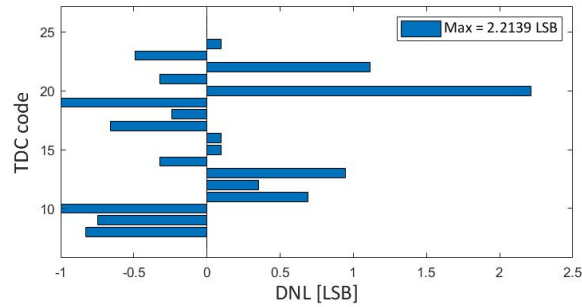
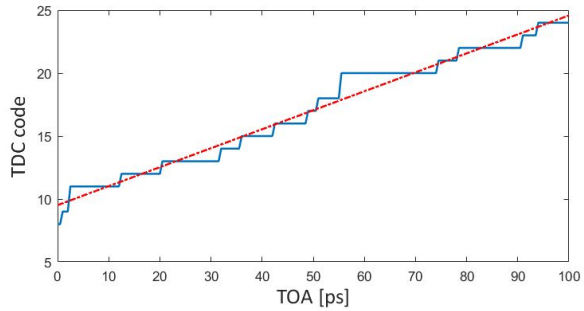


[1] C. Cottini, **E. Gatti**, and V. Svelto, "A new method for analog to digital conversion," Nucl. Instr. Meth., vol. 24, p. 241, Aug. 1963.

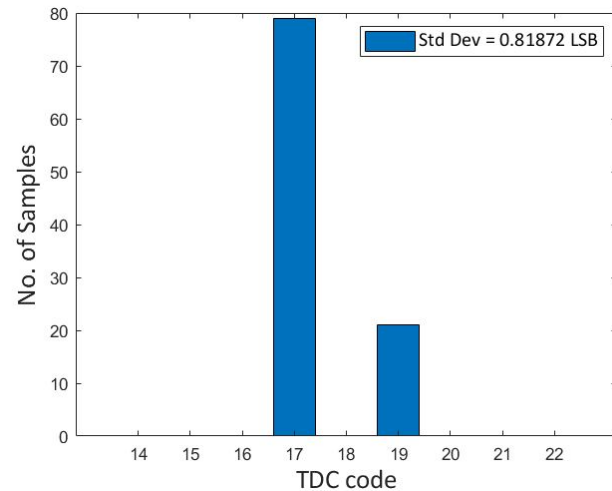
[2] **E. Gatti**, P. F. Manfredi, and D. Marino, "Analysis and characterization of cyclic-scale compensated analog-to-digital converters," Nucl. Instrum. Methods, vol. 165, no. 2, pp. 225–230, Oct. 1979.

28nm TDC Architecture – Sliding Scale

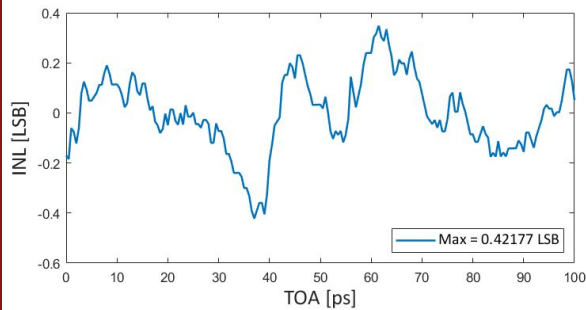
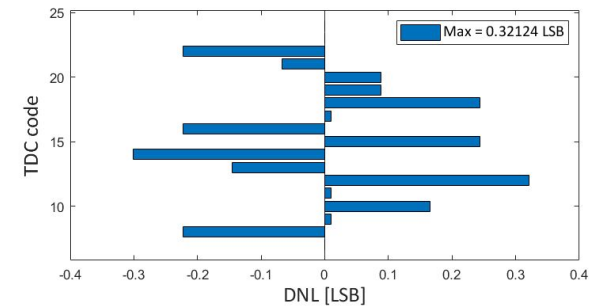
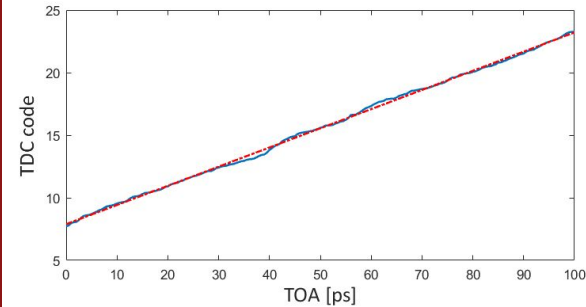
❑ TDC characteristics with sliding scale disabled



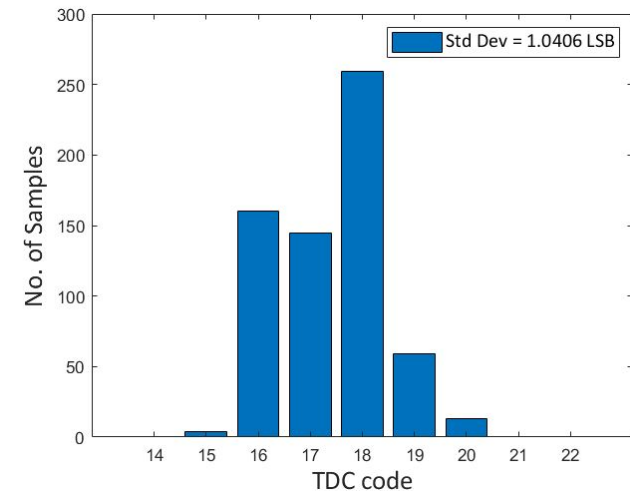
❑ Transient noise simulation – sliding scale disabled:



❑ Equivalent TDC characteristics with sliding scale enabled



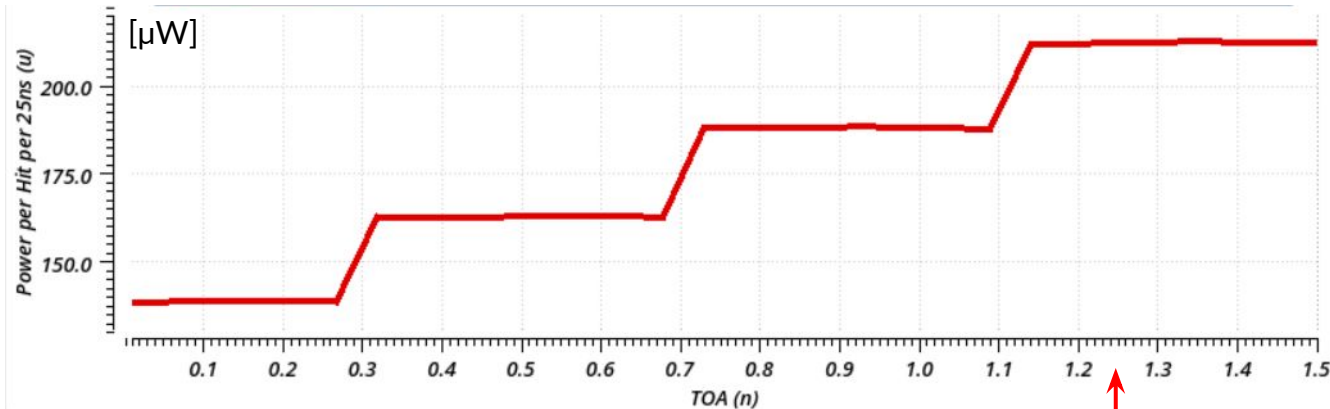
❑ Transient noise simulation – sliding scale enabled:



Sliding scale transforms the non-linearities into stochastic variable **thus effectively improving the conversion linearity at the expense of worsening single-shoot precision:**

28nm TDC – Power, Conversion Time, Area

- Average power within 25ns window VS TOA (RCX):



- TDC/channel idle consumption (due to leakage): $\sim 1.2\mu W$
- TDC/channel power consumption depends on time-interval being measured
 - For uniformly distributed time-intervals T_i the average power consumption per Hit in a 25ns measurement window is:

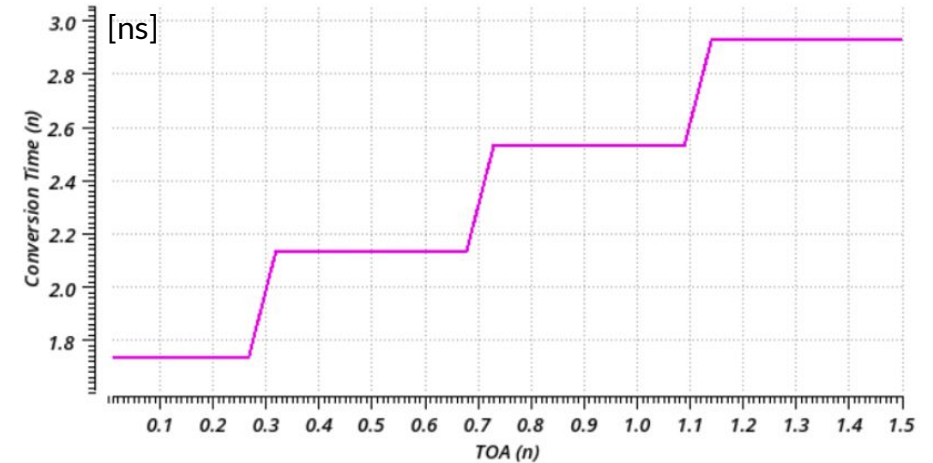
$$\frac{P_{av}}{\overline{hit}}/T_{CK} = 173\mu W$$

- Average power consumption:

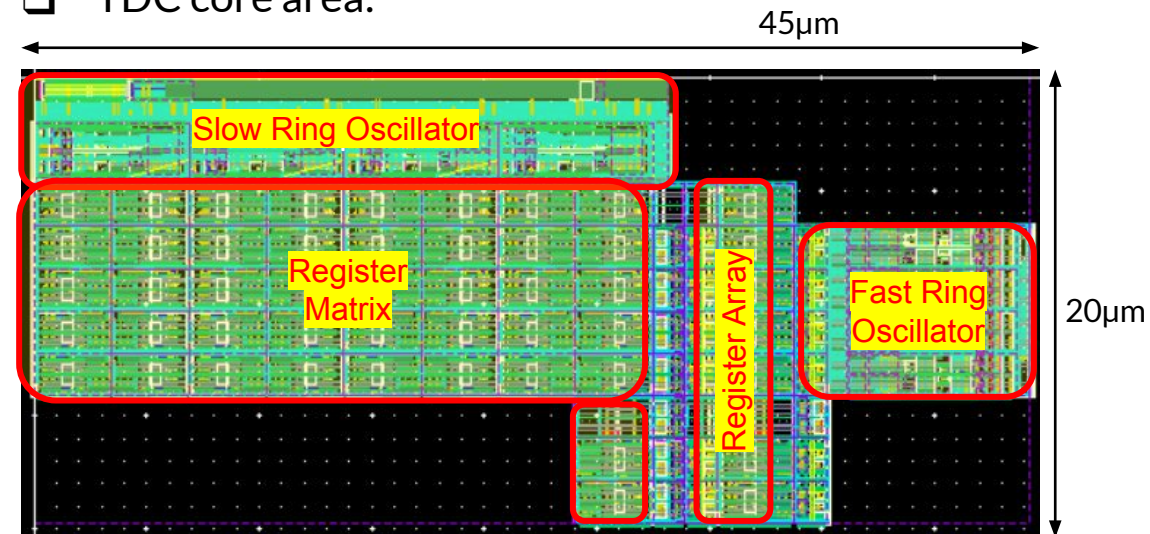
$$P_{av} = 1.2\mu W \cdot (1 - Occupancy) + \frac{P_{av}}{\overline{hit}}/T_{CK} \cdot Occupancy$$

- For 10% occupancy: $\sim 18.4\mu W$
- For 1% occupancy: $\sim 2.9\mu W$

- Time between Start signal and the end of conversion VS TOA (RCX):

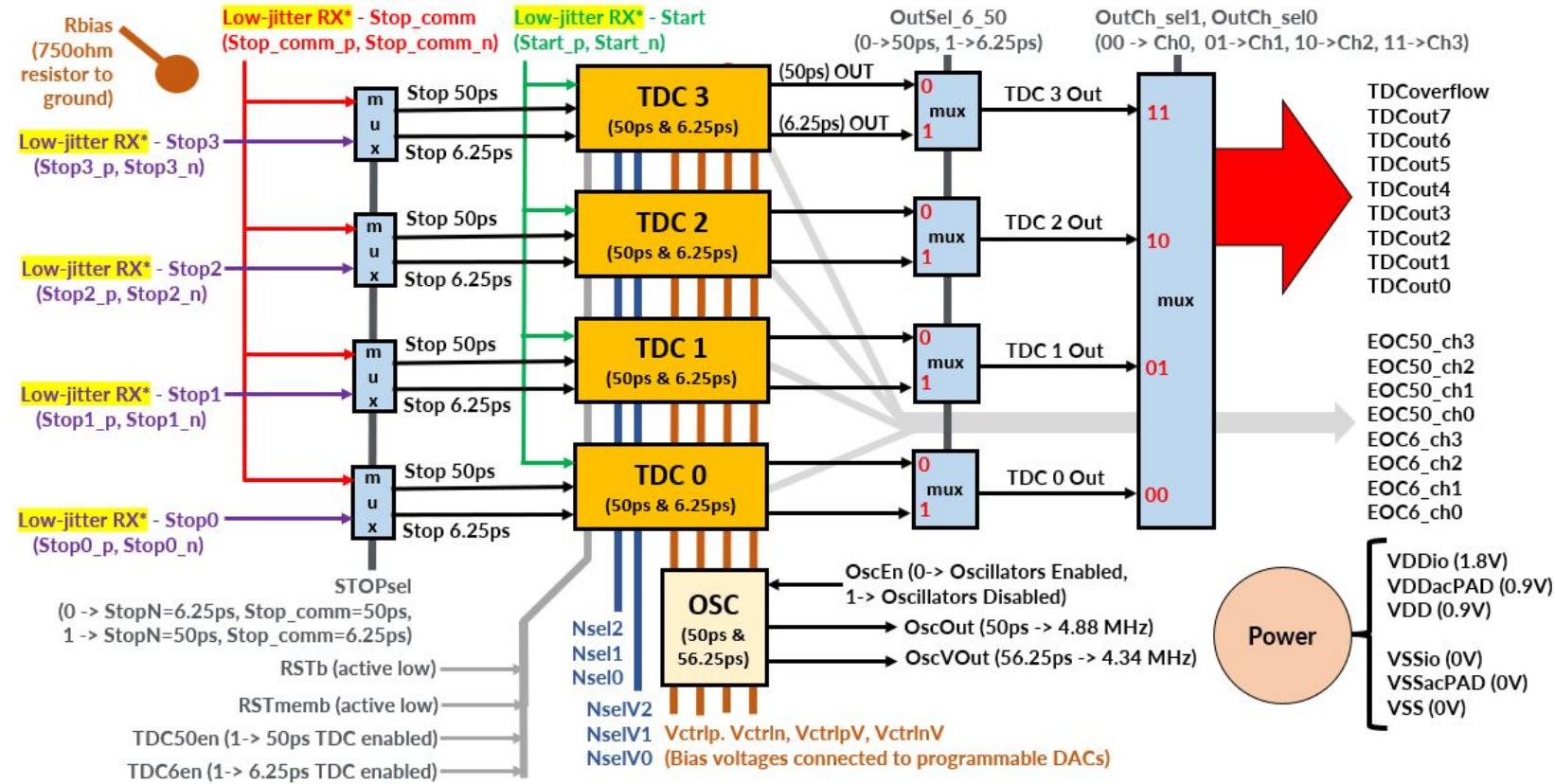



- TDC core area:



28nm TDC ASIC prototype

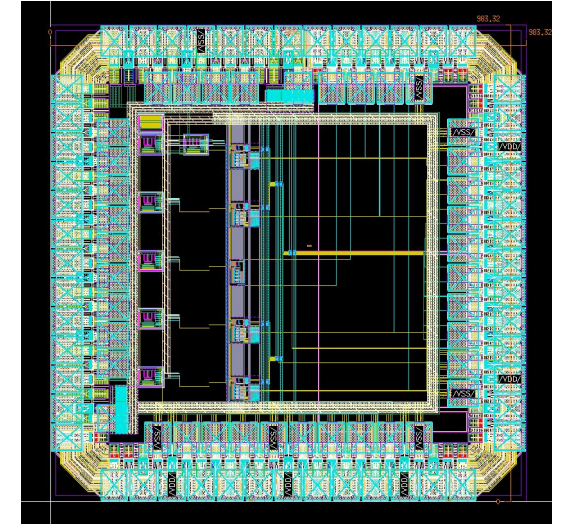
ASIC block schematic:



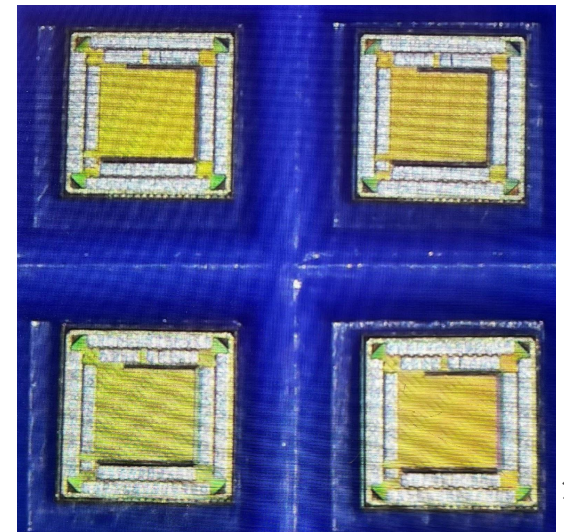
*courtesy of Carl Grace (LBNL) 

- 4 TDC channels, each with 50ps and 6.25ps sections
- Common Start, a common Stop1 and 4 separated Stop2 inputs
- Low-jitter receivers provided by LBNL
- Fast and Slow Oscillators for propagation delay control

ASIC layout:

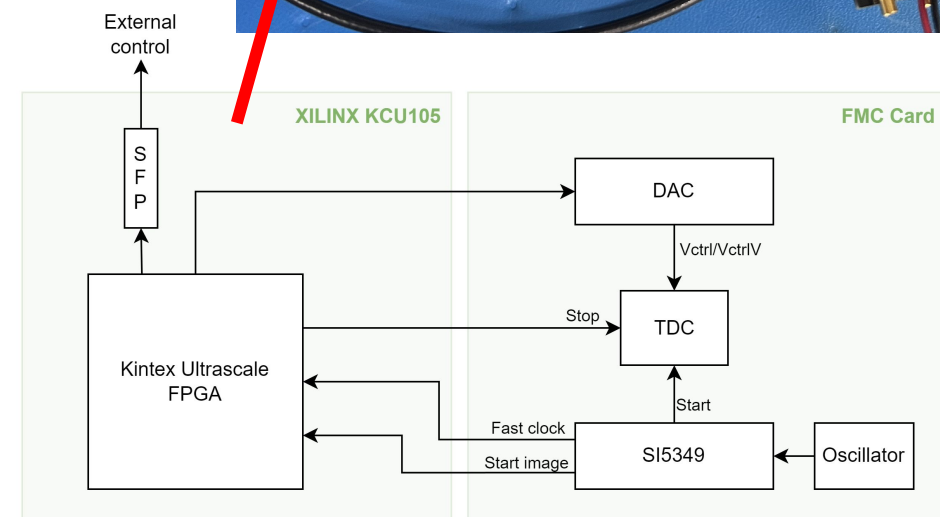
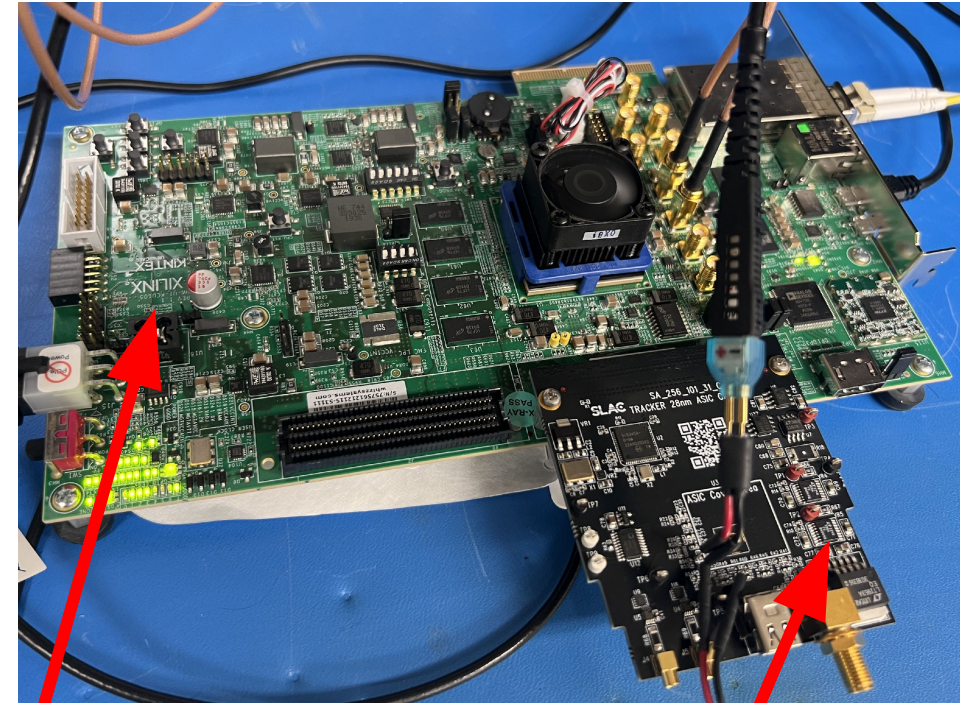


ASICs photo:



Development Board and custom ASIC Carrier

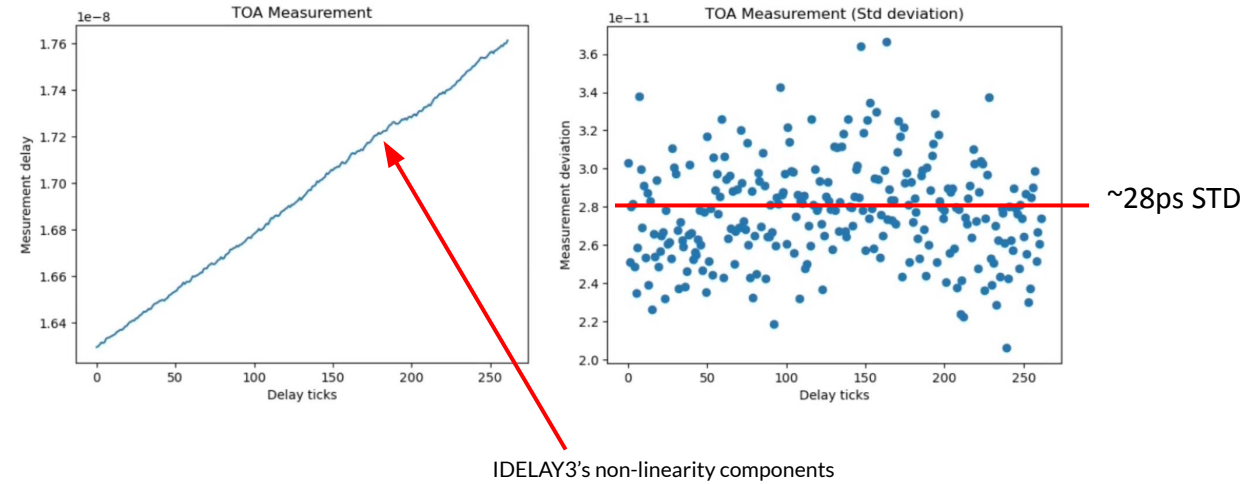
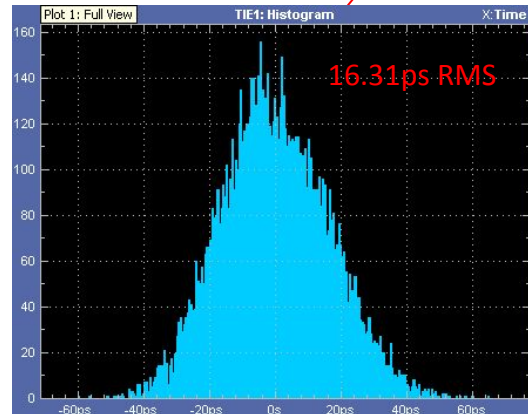
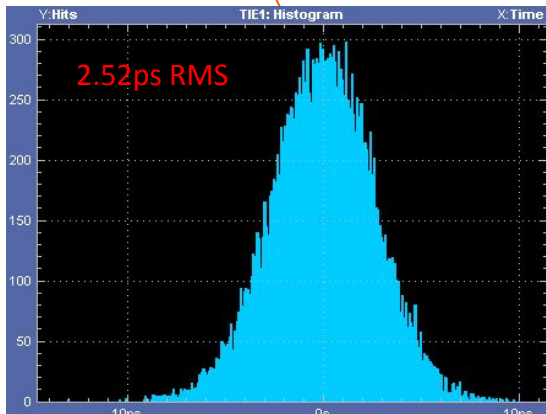
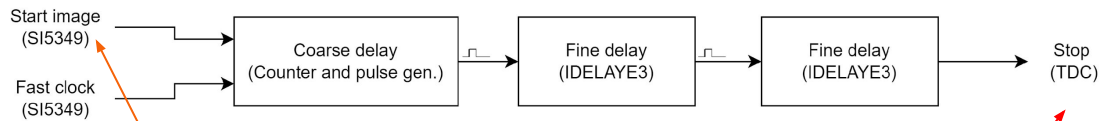
- AMD/Xilinx KCU105 development board for FPGA (KU040)
- FMC card for the ASIC carrier
 - Power regulation
 - Level translation
 - Low jitter PLL reference
 - Connectors for external reference and inputs option
- PLL (SI5349) provides start and stop signal sources:
 - Start signals directly comes from a PLL output
 - Jitter measurement: 2.6 ps-RMS
 - Output start images to the FPGA – constant phase
 - Provide fast clock signal that is used to shift the start signal
- DAC allows testing the ring oscillator reply in frequency
- External control through 10 Gbps serial link



FPGA Calibration pulse results and path forward

TOA measurements (calibration):

- Measured using high speed scope (Tektronix DPO7254)
- Averaged over 1000 samples
- Max. Std deviation of 35ps



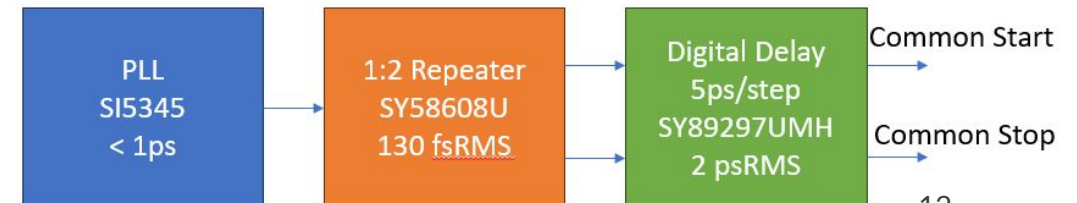
IDELAY3's non-linearity components

Status:

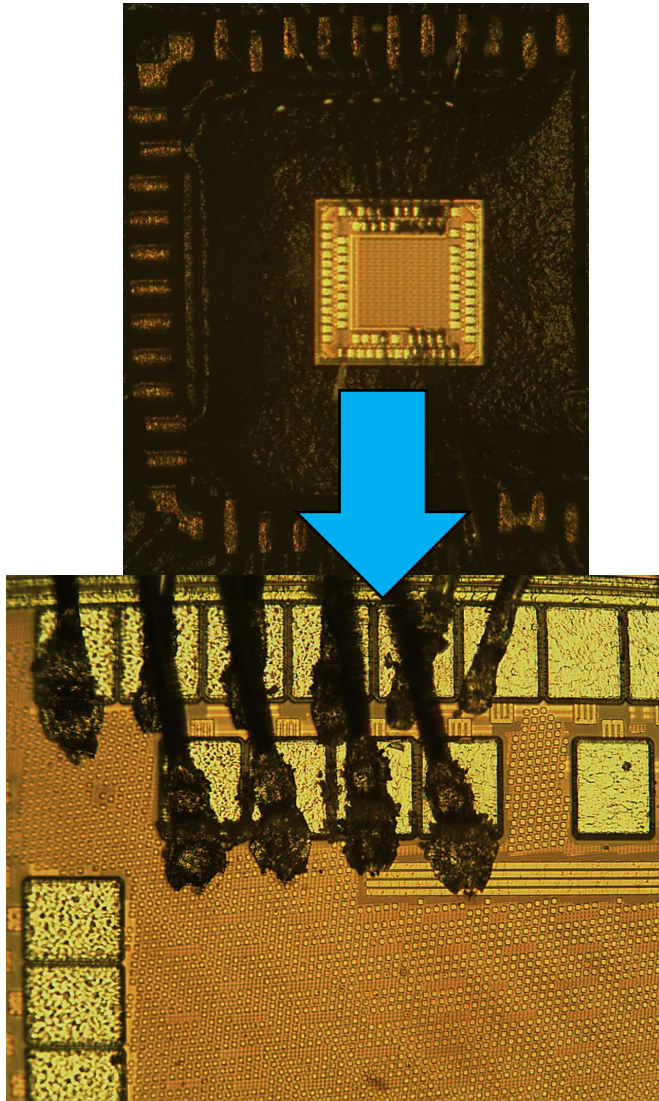
- Good enough for the 50ps/step linear sweeping
- But **not** good enough for 6.5ps/step
- Can be used to qualify the 50ps configuration

Path forward:

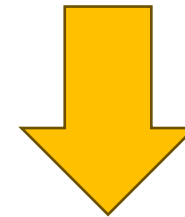
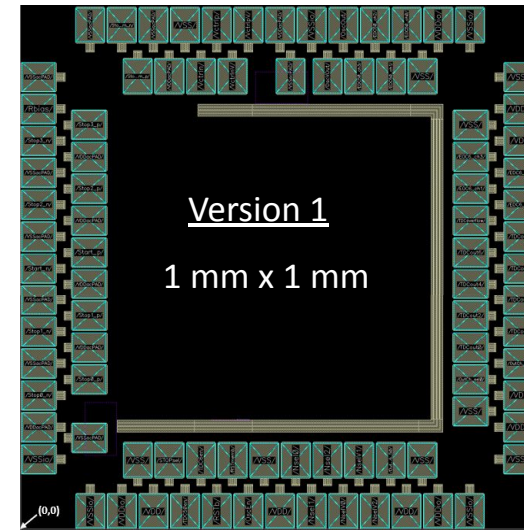
- Use of external delay line (SY89297UMH)



ASIC + PCB Wire bonding Issues



54 μm pitch (4 gap) and double row was too aggressive for the wire bonding pads



Retape out ASIC with less I/O pads, single row, and wider pitch



Summary and Future Plans

- **First tape out of 28nm at SLAC:**
 - As with any new technology node, there are large learning curves to overcome
- **Custom ASIC PCB carrier and FPGA firmware/software has been developed**
 - Calibration sweep circuit meets the 50ps/step requirement
 - Expecting much lower jitter in the common stop ($< 3\text{p-RSM}$) in the next ASIC carrier revision with new delay IC circuit
- **ASIC bonding pad placement was too aggressive in Version 1:**
 - Lesson learned: Getting feedback from wire bonding vendor and their recommendation prior to tape out
 - Version 2 will use a less aggressive pad pitch (Early 2024 tape out)

Backup

Linearity Improvement: Sliding-Scale

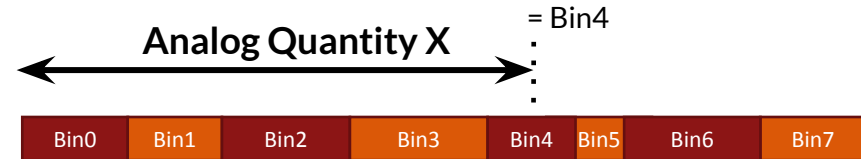


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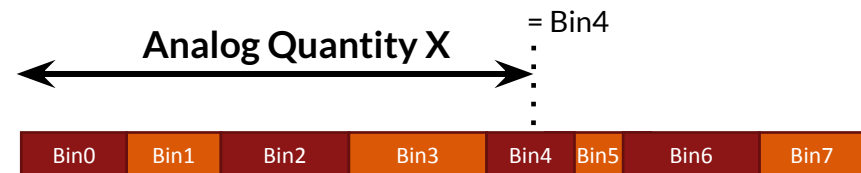
[2] E. Gatti, P. F. Manfredi, and D. Marino, "Analysis and characterization of cyclic-scale compensated analog-to-digital converters," Nucl. Instrum. Methods, vol. 165, no. 2, pp. 225–230, Oct. 1979.

Regular Converter:

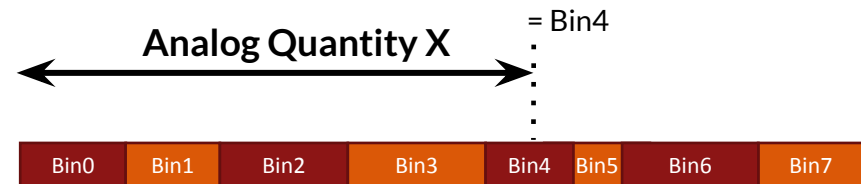
Measurement1:



Measurement2:



Measurement3:

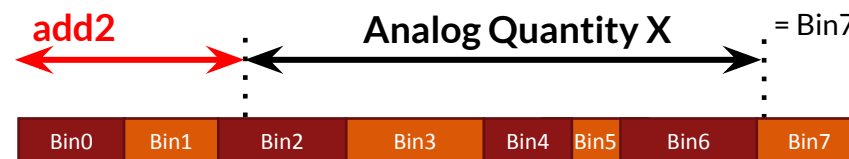


Sliding Scale [1][2]

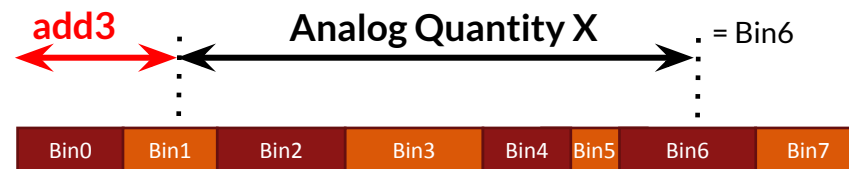
Result = Conversion - add



Result = 5 - 0 = 5



Result = 7 - 2 = 5



Result = 6 - 1 = 5

Readout Block Diagram

- **Controlled via an AXI-Lite bus:**
 - Configure TDC via memory mapped registers
 - Set DAC to configure the TDC's oscillators
 - Read TDC's oscillator frequency
 - Start and get status of custom FSMs
- **Start position finder:**
 - Search for the first non-overflow value
 - Generate stop pulse sync with start
 - Shift stop pulse by fast clock period steps
 - Set the 0 position with 5ps accuracy (IDEALYE3)
- **Scan and readout:**
 - Set fine delay position (increment of 5ps)
 - Generate AXI stream frame with position and TDCOut

